ABSTRACT OF THE DISCLOSURE

A method of manufacturing a chip-type ceramic electronic component having stable electrical properties and excellent mechanical strength includes the steps of providing a plurality of green sheets having predetermined cutting positions, coating inorganic paste including the same ceramic material as that included in ceramic green sheets, and an inorganic material having higher resistivity than that of the ceramic material, on a region of each ceramic green sheet, and laminating a predetermined number of the ceramic green sheets to form a ceramic laminated product. Then, the ceramic laminated product is cut into a chip at the predetermined cutting positions and sintered to form a ceramic sintered compact, and external electrodes are formed at both ends of the ceramic sintered compact.